

Chemical content BZX585-B3V3



Type number	Package	Package description	Total product weight
BZX585-B3V3	SOD523	SC-79	1.48454 mg

12NC	Version	Pb-free soldering			Pb soldering			Number of processing cycles	Assembly site	RHF-indicator
		MSL	PPT	MPPT	MSL	PPT	MPPT			
934055859135	14	1	260	30 s	1	235	20 s	3	D-22529 HAMBURG, Germany; Dongguan, China; Seremban, Malaysia	
934055859115	15	1	260	30 s	1	235	20 s	3	Seremban, Malaysia; Dongguan, China; D-22529 HAMBURG, Germany	

Subpart	Material group	Substances	CAS number	Mass(mg)	Mass(%) of subpart	Mass(%) of total product
Die	Doped silicon	Silicon (Si)	7440-21-3	0.05000	100.00000	3.36805
		subTotal		0.05000	100.00000	3.36805
Lead Frame	Copper alloy	Copper (Cu)	7440-50-8	0.45797	86.41000	30.84949
		Nickel (Ni) - cas no. 7440-02-0	7440-02-0	0.04648	8.77000	3.13100
		Tin (Sn)	7440-31-5	0.01187	2.24000	0.79971
	Pure metal layer	Silver (Ag)	7440-22-4	0.01367	2.58000	0.92109
		subTotal		0.53000	100.00000	35.70129
Mould Compound	Filler	Silica fused	60676-86-0	0.62480	71.00000	42.08711
	Pigment	Carbon black	1333-86-4	0.00264	0.30000	0.17783
	Polymer	Epichlorohydrin/o-Cresol/Formaldehyde polymer (generic)	29690-82-2	0.17336	19.70000	11.67769
		Phenolic resin	Proprietary	0.07920	9.00000	5.33499
subTotal		0.88000	100.00000	59.27762		
Post-Plating	Impurity	Antimony (Sb)	7440-36-0	0.00000	0.01000	0.00013
		Bismuth (Bi)	7440-69-9	0.00000	0.02000	0.00027
		Iron (Fe)	7439-89-6	0.00000	0.01000	0.00013
		Lead (Pb)	7439-92-1	0.00000	0.01000	0.00013
	Tin solder	Tin (Sn)	7440-31-5	0.01999	99.95000	1.34655
		subTotal		0.02000	100.00000	1.34721
Wire	Impurity	Non hazardous	Proprietary	0.00000	0.01000	0.00003
	Pure metal	Gold (Au)	7440-57-5	0.00454	99.99000	0.30599
		subTotal		0.00454	100.00000	0.30602

Note(s):

1) This is a generic description of the substance used as the actual composition of the substances are either considered proprietary or no official CAS number is available. If a CAS number is given, it is the closest match available.

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